Product Change Notification

Change Notification #:	**116060 - 01**
Change Title:	**Intel® Ethernet Converged Network Adapter X540 - T1 Product Code X540T1G1P5 MM#914242 Intel® Ethernet Converged Network Adapter X540 - T2 Product Code X540T2G1P5 MM#914244 Intel® Ethernet Converged Network Adapter X540 - T1 Product Code X540T1BLK MM#927235 Intel® Ethernet Converged Network Adapter X540 - T2 Product Code X540T2BLK MM# 927245 Intel® Ethernet Converged Network Adapter X540 - T1 Product Code X540T1 MM#914246 Intel® Ethernet Converged Network Adapter X540 - T2 Product Code X540T2 MM#914248, PCN 116060-01, Product Material, Label, Silicon change to Lead Free Reason for Revision: Extending the Customer readiness date to September 2018**
Date of Publication:	**February 09, 2018**

Key Characteristics of the Change:

Product Material, Label

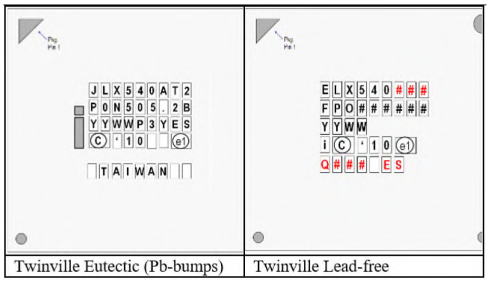
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	**September 01, 2018**

Description of Change to the Customer:

Reason for Revision: Extending the Customer ready date out to September 1, 2018.
These Intel products will undergo the following changes:

1. As per the Intel Corporate Green Initiative, Intel is moving its products to a RoHS Compliant 100% lead-free process which impacted several of the flip-chip silicon product lines. The current silicon products are listed as 'exempt' based on the EU RoHS exemption for FLI leaded parts. This change removed that RoHS exemption. There is no impact on the silicon's function, electrical performance, mechanical use or stated reliability. Intel has qualified and certified this change in the same way as all products supplied to our customers. There is no form-fit-function change for any of the impacted silicon. FLI (First Level Interconnect) material will change from Lead (Pb) based solder bump technology to Pb-Free (Sn/Ag) technology. There is no change to the second level interconnects for these products. This change affects First Level Interconnects only. The transition from eutectic to lead free at the FLI style of the product marking will change. The mark will go to a laser mark on swatch versus an ink stamp on substrate as illustrated below.



Twinville Eutectic (Pb-bumps) | Twinville Lead-free

2. As a result of these changes, the PBA (printed board assembly) and TA (top assembly) numbers will roll as noted in the affected products table within this PCN. If the PBA/TA numbers are printed on any product or box labels, those will show the PBA/TA dash roll as well.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.
The customer can expect to receive mixed inventory.
Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Marketing Name	**Product Code**	**MM#**	**Pre Change TA**	**Pre Change PBA**	**Post Change TA**	**Post Change PBA**
Intel® Ethernet Converged Network Adapter X540 - T1 OEM Gen	X540T1G1P5	914242	G54504-006	G54369-007	G54504-007	G54369-008
Intel® Ethernet Converged Network Adapter X540 – T2 OEM Gen	X540T2G1P5	914244	G45588-005	G36748-007	G45588-006	G36748-008
Intel® Ethernet Converged Network Adapter X540 - T1 Retail	X540T1	914246	G56796-006	G54042-007	G56796-007	G54042-008
Intel® Ethernet Converged Network Adapter X540 – T2 Retail	X540T2	914248	G45789-004	G45270-005	G45789-005	G45270-006
Intel® Ethernet Converged Network Adapter X540 - T1 Retail	X540T1BLK	927235	G90120-003	G54042-007	G90120-004	G54042-008
Intel® Ethernet Converged Network Adapter X540 – T2 Retail	X540T2BLK	927245	G90121-003	G45270-005	G90121-004	G45270-006

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
February 9, 2018	00	Originally Published PCN
March 20, 2018	**01**	**Extending the Customer ready date out to September 1, 2018**

Product Change Notification

116060 - 01

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
Europe Email: eccb@intel.com
Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2018. Other names and brands may be claimed as the property of others.

3D XPoint, Axxia, Basis, Basis Peak, BlueMoon, BunnyPeople, Celeron, Centrino, Cilk, Curie, Flexpipe, Intel, the Intel logo, Intel Atom, Intel CoFluent, Intel Core, Intel. Experience What's Inside, the Intel. Experience What's Inside logo, Intel Inside, the Intel Inside logo, Intel Insider, Intel Joule, Intel RealSense, Intel SingleDriver, Intel SpeedStep, Intel Unite, Intel vPro, Intel Xeon Phi, Intel XScale, InTru, the InTru logo, the InTru Inside logo, InTru soundmark, Iris, Itanium, MCS, MMX, Optane, Ostro, Pali, Pentium, picoArray, Picochip, picoXcell, Puma, Quark, SMARTi, Soletta, Sound Mark, StarPro, Stay With It, the Engineering Stay With It logo, StreamSight, Tarari, The Journey Inside, Thunderbolt, the Thunderbolt logo, Transcede, True Key, Ultrabook, VTune, Xeon, X-GOLD, XMM, X-PMU and XPOSYS are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.
Microsoft, Windows, and the Windows logo are trademarks, or registered trademarks of Microsoft Corporation in the United States and/or other countries. Java is a registered trademark of Oracle and/or its affiliates. Bluetooth is a trademark owned by its proprietor and used by Intel Corporation under license. Intel Corporation uses the Palm OS* Ready mark under license from Palm, Inc. OpenCL and the OpenCL logo are trademarks of Apple Inc. used by permission by Khronos.
Learn how to use Intel Trademarks and Brands correctly at http://www.intel.com/intel/legal/tmusage2.htm.